

ABSTRACT OF THE DISCLOSURE

A device for compensating for heat generation in a modular IC test handler is provided which includes at least one supporting member positioned adjacent to a press unit of the handler, and having a cooling fluid flow passage formed therein for flow of cooling fluid, and a plurality of cooling fluid spraying units for spraying the cooling fluid supplied through the cooling fluid flow passage toward faces of modular ICs in an oblique direction from a position between adjacent push bars of the press unit, thereby spraying cooling fluid directly onto ICs attached to a surface of modular ICs during testing and enhancing an efficiency of heat compensation.